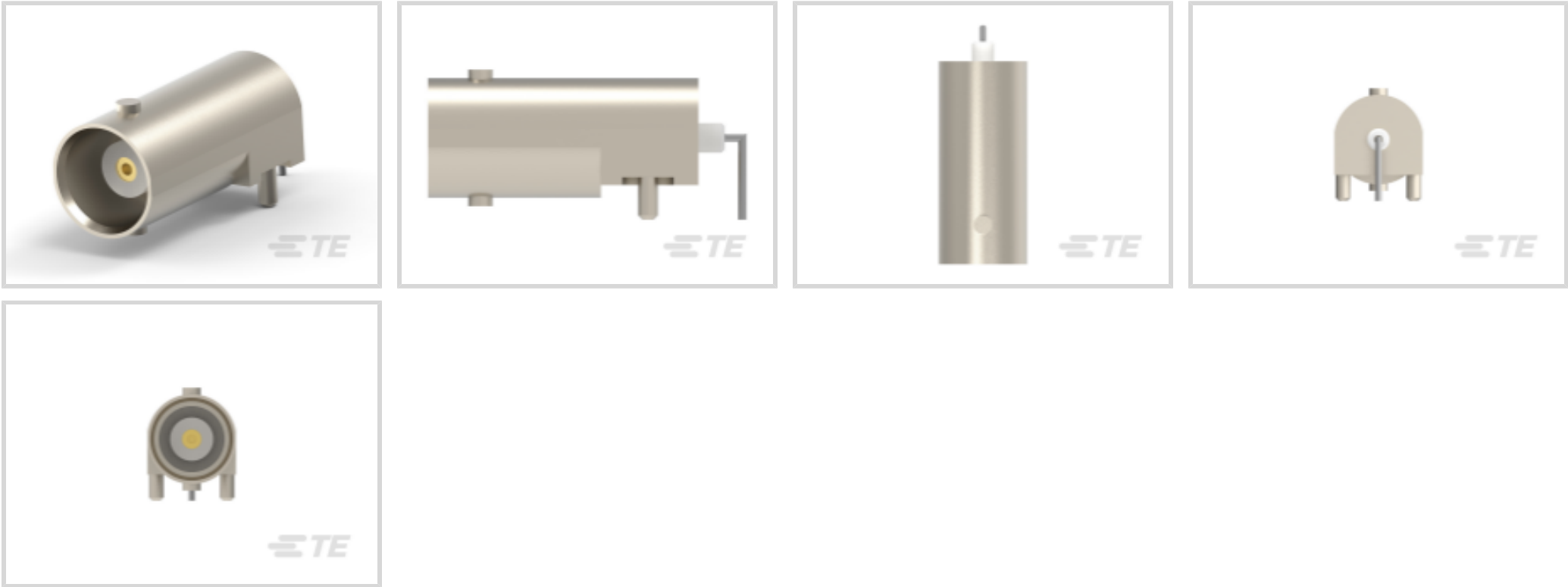




Connectors > RF Connectors > Coax Connectors > BNC RF Connector: Male (Jack), Right Angle



RF Interface: **BNC**

RF Connector Style: **Jack**

RF Connector Mated Outer Diameter (Approximate): **14.53 mm [.572 in]**

Impedance: **50 Ω**

RF Connector Coupling Mechanism: **Bayonet**

[All BNC RF Connector: Male \(Jack\), Right Angle \(30\)](#)

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector Shape | Circular |
| RF Interface | BNC |
| RF Connector Style | Jack |
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------|-------------|
| PCB Mount Orientation | Right Angle |
| Number of Positions | 1 |
| Number of Coaxial Contacts | 1 |

Electrical Characteristics

| | |
|-----------|------|
| Impedance | 50 Ω |
|-----------|------|

Body Features

| | |
|--|--|
| | |
|--|--|



| | |
|---------------|------|
| Body Material | Zinc |
|---------------|------|

| | |
|-----------------------|--------|
| Body Plating Material | Nickel |
|-----------------------|--------|

Contact Features

| | |
|---|--------|
| RF Connector Center Contact Underplating Material | Nickel |
|---|--------|

| |
|--------|
| 30 µin |
|--------|

| | |
|--|-----------|
| RF Connector Center Contact Plating Material | Gold (Au) |
|--|-----------|

| | |
|--------------------------------------|-----------------|
| RF Connector Center Contact Material | Phosphor Bronze |
|--------------------------------------|-----------------|

Termination Features

| | |
|---------------------------|-----------------------|
| Termination Method to PCB | Through Hole - Solder |
|---------------------------|-----------------------|

| | |
|--------------------------------|------------------|
| Termination Post & Tail Length | 2.79 mm[.109 in] |
|--------------------------------|------------------|

Mechanical Attachment

| | |
|---------------------|---------|
| PCB Mount Retention | Without |
|---------------------|---------|

| | |
|---------------------------------|---------|
| RF Connector Coupling Mechanism | Bayonet |
|---------------------------------|---------|

| | |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

| | |
|-------------------------------|------------|
| RF Contact Captivation Method | Mechanical |
|-------------------------------|------------|

| | |
|--------|------|
| Detent | With |
|--------|------|

Dimensions

| | |
|-------------------------|-----------------|
| Profile Height from PCB | 8.64 mm[.34 in] |
|-------------------------|-----------------|

| | |
|---|-------------------|
| RF Connector Mated Outer Diameter (Approximate) | 14.53 mm[.572 in] |
|---|-------------------|

Usage Conditions

| | |
|-------------------|-------------|
| Insulation Option | Uninsulated |
|-------------------|-------------|

Operation/Application

| | |
|---------------------|-------|
| Operating Frequency | 4 GHz |
|---------------------|-------|

Packaging Features

| | |
|------------------|------|
| Packaging Method | Tray |
|------------------|------|

Other

| | |
|-------|------------|
| Grade | Commercial |
|-------|------------|

| | |
|---------------------|-------------------|
| Dielectric Material | Polymethylpentene |
|---------------------|-------------------|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|------------------------------|-----------|
| EU RoHS Directive 2011/65/EU | Compliant |
|------------------------------|-----------|



| | |
|---|--|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Wave solder capable to 265°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought

Documents

Product Drawings



JACK,PCB,50 OHM,BNC

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_414373-1_M.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_414373-1_M.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_414373-1_M.3d_stp.zip

English

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Product Specifications

Product Specification

English

Product Specification

English